## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	I <sub>D</sub>
150V	3.8mΩ@10V	235A



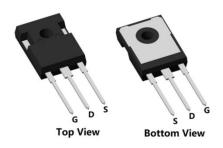
#### **Feature**

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

## **Applications**

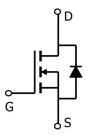
- PWM Application
- Hard switched and high frequency circuits
- Power Management

## **Package**

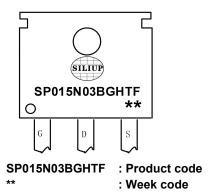


TO-247(1:G 2:D 3:S)

## Circuit diagram



#### Marking



#### **Order Information**

Device	Package	Unit/Tube
SP015N03BGHTF	TO-247	30

150V N-Channel Power MOSFET

## Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	150	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current (Tc=25℃)	ID	235	А
Continuous Drain Current (Tc=100°C)	ID	160	А
Pulsed Drain Current	I <sub>DM</sub>	940	А
Single Pulse Avalanche Energy <sup>1</sup>	Eas	1681	mJ
Power Dissipation (Tc=25℃)	P <sub>D</sub>	430	W
Thermal Resistance Junction-to-Case	R <sub>0</sub> JC	0.29	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature Range	TJ	-55 to 150	℃

## Electrical characteristics (Ta=25°C, unless otherwise noted)

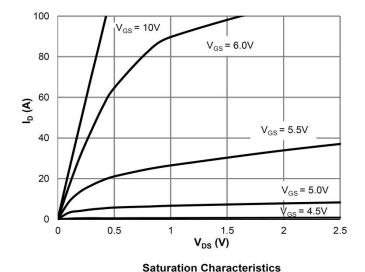
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	ID = 250µA, VGS = 0V		-	-	٧
Drain-Source Leakage Current	I <sub>DSS</sub>	VDS = 80V, VGS = 0V	-	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	VGS = ±20V, VDS = 0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	VDS = VGS, ID = 250µA	2.5	3.5	4.5	٧
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	VGS = 10V, ID = 20A	-	3.8	4.3	mΩ
Dynamic characteristics					•	
Input Capacitance	Ciss	VDS=75V , VGS=0V , f=1MHz		8538	-	
Output Capacitance	Coss			772	-	pF
Reverse Transfer Capacitance	Crss			21	-	
Total Gate Charge	Qg	VDS=75V , VGS=10V , ID=20A		122	-	
Gate-Source Charge	Q <sub>gs</sub>			48	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	33	-	
Switching Characteristics						
Turn-On Delay Time	T <sub>d(on)</sub>		-	33	-	
Rise Time	Tr	VDD=75V, VGS=10V , RG=3.0Ω, ID=20A		59	-	
Turn-Off Delay Time	T <sub>d(off)</sub>			89	-	nS
Fall Time	T <sub>f</sub>			48	-	
Diode Characteristics						
Diode Forward Voltage	V <sub>SD</sub>	VGS=0V , I <sub>S</sub> =1A , TJ=25℃	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	235	Α
Reverse Recovery Time	Trr	I <sub>S</sub> =15A, di/dt=100A/us, TJ=25℃		112	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>			426	-	nC

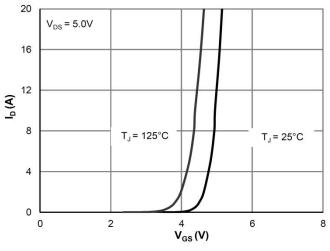
#### Note:

1. The test condition is VDD=50V,VGS=10V,L=0.5mH,RG=25 $\Omega$ 



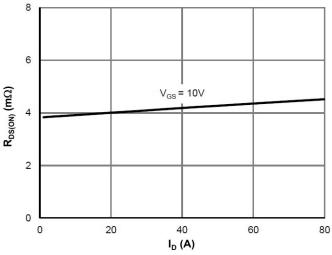
#### **Typical Characteristics**



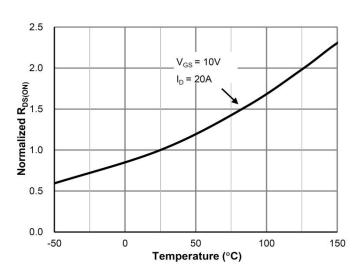


**Transfer Characteristics** 

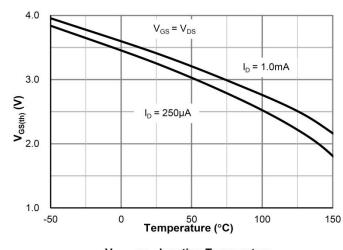




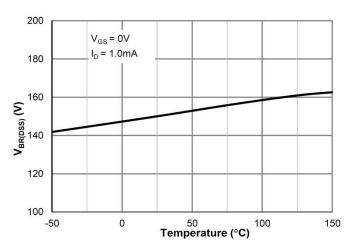




 $R_{DS(ON)}$  vs. Junction Temperature

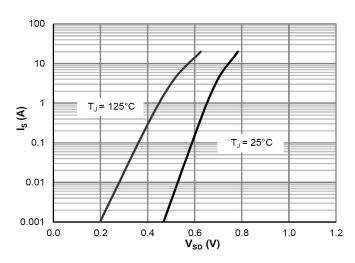


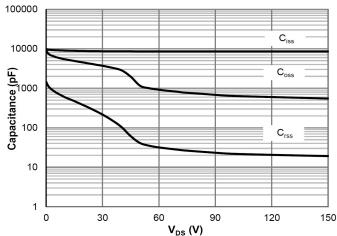
 $V_{\text{GS(th)}}$  vs. Junction Temperature



 $V_{\text{BR}(\text{DSS})}$  vs. Junction Temperature

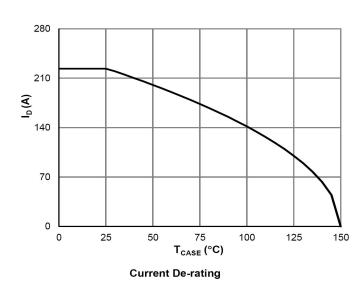
#### 150V N-Channel Power MOSFET

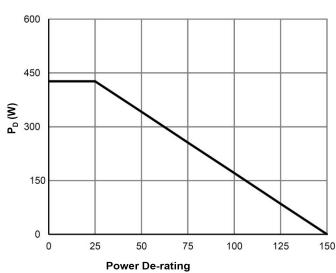


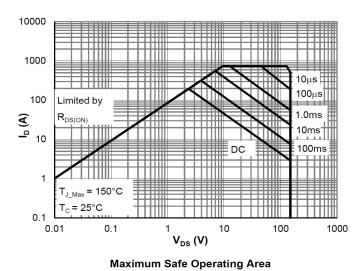


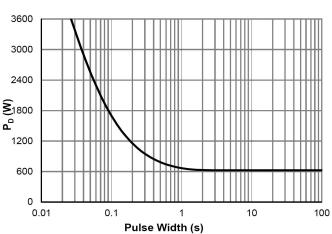
**Body-Diode Characteristics** 

**Capacitance Characteristics** 

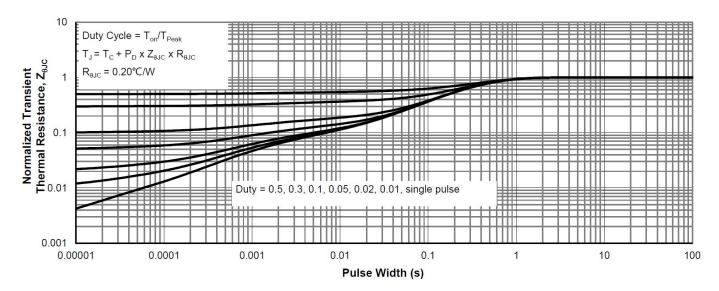






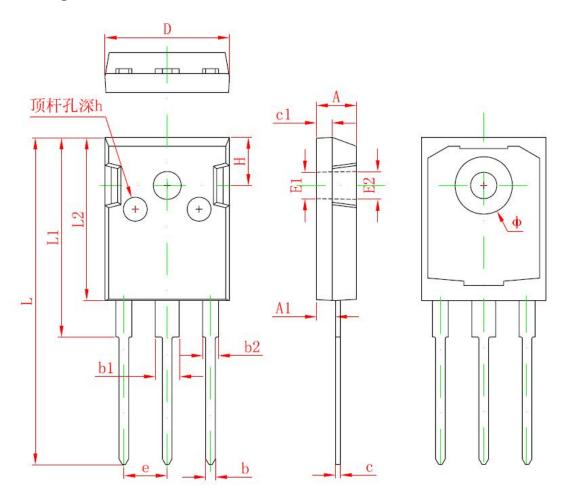


Single Pulse Power Rating, Junction-to-Case



**Normalized Maximum Transient Thermal Impedance** 

# **TO-247 Package Information**



Symbol	Dimensions In Millimeters		<b>Dimensions In Inches</b>	
	Min.	Max.	Min.	Max.
А	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
С	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF.		0.138 REF.	
E2	3.600 REF.		0.142 REF.	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Ф	7.100	7.300	0.280	0.287
е	5.450 TYP.		0.215 T	YP.
Н	5.980 REF.		0.235 F	REF.
h	0.000	0.300	0.000	0.012